



Final Product Change Notification

202003043F01

Issue Date: 13-May-2020

Effective Date: 11-Aug-2020

Dear *Gordon Love*,

Here's your personalized quality information concerning products Premier Farnell PLC purchased from NXP.

For detailed information we invite you to [view this notification online](#)

This notice is NXP Company Proprietary.



Management Summary

Cu Wire is being added as a wirebond material option for LPC5410x, LPC5411x and LPC51U68 in LQFP64 packages at assembly site NXP-ATKH.

Change Category

- | | | | | |
|--|--|---|---|---|
| <input type="checkbox"/> Wafer Fab Process | <input type="checkbox"/> Assembly Process | <input checked="" type="checkbox"/> Product Marking | <input type="checkbox"/> Test Location | <input type="checkbox"/> Design |
| <input type="checkbox"/> Wafer Fab Materials | <input checked="" type="checkbox"/> Assembly Materials | <input type="checkbox"/> Mechanical Specification | <input type="checkbox"/> Test Process | <input type="checkbox"/> Errata |
| <input type="checkbox"/> Wafer Fab Location | <input type="checkbox"/> Assembly Location | <input type="checkbox"/> Packing/Shipping/Labeling | <input type="checkbox"/> Test Equipment | <input type="checkbox"/> Electrical spec./Test coverage |
| <input type="checkbox"/> Firmware | <input type="checkbox"/> Other | | | |

LPC5410x, LPC5411x,
LPC51U68 LQFP64
Package Cu Wire
Qualification for NXP-
ATKH

Description of Change

Copper wire has been qualified and will be added as a wirebond material. Upon effective date, NXP will begin shipping product with copper wire.

Die attach glue and mold compound have been upgraded to support copper wire.

See attached Self Qualification Reports (SQR) for details of the reliability qualification test results.

Samples of the following superset part numbers will be available:
LPC54114J256BD64

LPC54102J512BD64

LPC51U68FBD64

Reason for Change

Adding Copper wire is for supply assurance.

Identification of Affected Products

Top side marking

Product version is incremented. See marking details in attached Self Qualification Report (SQR) document.

Product Availability

Sample Information

Samples are available from 22-May-2020

Production

Planned first shipment 09-Aug-2020

Anticipated Impact on Form, Fit, Function, Reliability or Quality

The top side marking, wire composition, die attach glue and mold compound are the only changes. No Impact to fit, function or reliability.

Data Sheet Revision

No impact to existing datasheet

Disposition of Old Products

Existing inventory will be shipped until depleted

Additional information

Affected products and sales history information: see attached file

Self qualification: [view online](#)

Additional documents: [view online](#)



Timing and Logistics

In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by 12-Jun-2020.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please [contact NXP "Global Quality Support Team"](#).

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

Name Tim Camenzind

Position Quality Manager

e-mail address tim.camenzind@nxp.com

At NXP Semiconductors we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards.

Customer Focus, Passion to Win.

NXP Quality Management Team.

About NXP Semiconductors

NXP Semiconductors N.V. (NASDAQ: NXPI) provides High Performance Mixed Signal and Standard Product solutions that leverage its leading RF, Analog, Power Management, Interface, Security and Digital Processing expertise. These innovations are used in a wide range of automotive, identification, wireless infrastructure, lighting, industrial, mobile, consumer and computing applications.

You have received this email because you are a designated contact or subscribed to NXP Quality Notifications. NXP shall not be held liable if this Notification is not correctly distributed within your organization.

This message has been automatically distributed. Please do not reply.

[View Notification](#)

[Subscription](#)

[Support](#)

[NXP](#) | [Privacy Policy](#) | [Terms of Use](#)

NXP Semiconductors
High Tech Campus, 5656 AG Eindhoven, The Netherlands

© 2006-2010 NXP Semiconductors. All rights reserved.